

WHAT IS CLAIMED IS:

1. A resin powder for a dermatologic composition, which comprises resin particles having an average volume particle size of 2.0 to 20.0 μm , a shape factor SF1 of 110 to 140 and an average volume particle size distribution GSDv of 1.3 or less.

2. The resin powder of Claim 1, wherein the resin particles further have a surfaceness index of 2.0 or less.

3. The resin powder of Claim 1, wherein the resin particles further have an average number particle size distribution GSDp of 1.5 or less.

4. The resin powder of Claim 1, wherein a volumetric ratio of the resin particles having a volume particle size of 20 μm or greater is 3% or less.

5. The resin powder of Claim 1, wherein the resin has a number-average molecular weight of 3,000 to 20,000.

6. The resin powder of Claim 1, wherein the resin has a weight-average molecular weight of 6,000 to 100,000.

7. The resin powder of Claim 1, wherein the resin has a glass transition temperature ranging from 40 to 100°C.

8. The resin powder of Claim 1, which have a compaction ratio of 0.6 or less.

9. The resin powder of Claim 1, wherein the resin particles have a water content of 3 wt.% or less.

10. The resin powder of Claim 1, wherein a volatile content in the resin particles is 100 ppm or less.

11. The resin powder of Claim 1, wherein the resin constituting the resin particles has an acid value ranging from 1.0 to 20 mg/KOH/g.

12. The resin powder of Claim 1, wherein a solution, obtained by dissolving 1 g of the resin powder in 3 g of acetone, adding 25 g of deionized water to the resulting solution to give a precipitate and filtering the precipitate thus formed has a surface tension of 20 mN or greater.

13. The resin powder of Claim 1, wherein a solution, obtained by dissolving 1 g of the resin powder in 3 g of acetone, adding 25 g of deionized water to the resulting solution to give a precipitate and filtering the precipitate thus formed has a conductivity of 100 μ S or less.

14. The resin powder of Claim 12, wherein the solution has a conductivity of 100 μ S or less.

15. The resin powder of Claim 12, wherein the resin particles has other fine particles adhered thereto.

16. The resin powder of Claim 15, wherein the resin particles and the fine particles are used in combination so as to satisfy the following formula: (volume average particle size of the

resin particles) / (volume average particle size of the fine particles) ≥ 2 .

17. The resin powder of Claim 15, wherein a weak adhesive strength ratio of the fine particles to the resin particles is 90% or less.

18. A cosmetic composition comprising a resin powder for a dermatologic composition as claimed in Claim 1.

19. The cosmetic composition of Claim 18, wherein the content of the resin powder is from 0.1 to 90 wt.% of the composition.

20. A skin cleansing composition, comprising a resin powder for a dermatologic composition as claimed in Claim 1.

21. The skin cleansing composition of Claim 20, wherein the content of the resin powder is from 0.1 to 90 wt.% of the composition.

22. A process for preparing a resin powder for a dermatologic composition as claimed in Claim

1, which comprises preparing a dispersion of resin particles by emulsion polymerization and allowing the resin particles to undergo agglomeration.